



## Hydrosoluble Flux

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# FLUX TYPE H35M

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**H35M** Flux is a mildly active, low halide hydrosoluble flux for use in flow soldering equipment for the production of printed circuit boards. This mild hydrosoluble flux is more effective than rosin based flux in removing oxides from the surfaces to be soldered particularly in the case of bare copper.

- De-oxidising flux used for soldering printed circuits
- Non rosin, organic flux, soluble in water.
- Meets standards NFC 90550, DIN 8511 –8516 and others

### Physiochemical Characteristics:

- Solution : Alcoholised
- Colour : Colourless
- Density at 20°C : 0.970
- Acid number (IA) :  $112 \pm 4$  mg/g
- Chloride content : < 0.05 %
- Density adjustment : D305 Dilutant
- Perfect cleaning by water

### Instructions of Use:

For use in automatic flow machines, being applied by the air foam process.

Pre-heating temperature should be between 80°C and 90°C, and the alloy bath temperature between 235°C and 250°C.

Density must be regularly controlled. D 305 Dilutant must be used to adjust density.

Cleaning can be carried out in water, without saponifier, in a closed loop system incorporating an ion exchange column.

In case of an opened cleaning system, comply with the regulations in force.

### Miscellaneous:

**Health and Safety:** As with all soldering fluxes, MBO H35M must be used in a well ventilated area away from any source of flame or ignition.

**Packaging:** Throwaway plastic containers of 5, 10 and 20 litres.

**Storage:** In original hermetically sealed containers, stored at an ideal temperature of around 20°C for 12 months maximum.